Sputtering Equipment FHR.Line.1100.V

In-Line Sputtering Equipment vertical, 7° inclined to the front side for the deposition of Dielectric Coatings



General Description

Sputtering machine for the deposition of metals, alloys or compound layers, preferably on planar substrates on carriers able to run in MF carrier transport is vertical, 7° inclinded to the front side

The system is built of rectangular recipients (modules). The modules in the lock section are separated from each other by rectangular valves designed for a very low particle emission. Further process units with additional deposition sources can be created optional at a later time by adding additional modules.

The system is also equipped with two cross transportation modules used for loading and unloading of the substrates and a carrier return system.

The Equipment consists of the following modules:

- Module 1: loading station
- Module 2: input load lock
- Module 3: buffer chamber 1
- Module 4: buffer chamber 2
- Module 5: sputtering pseudo reactive
- Module 6: buffer chamber as gas separation
- Module 7: sputtering reactive
- Module 8: output load lock
- Module 9: unloading station
- Module for substrate load/unload of carriers using 2 midsized Kuka robots

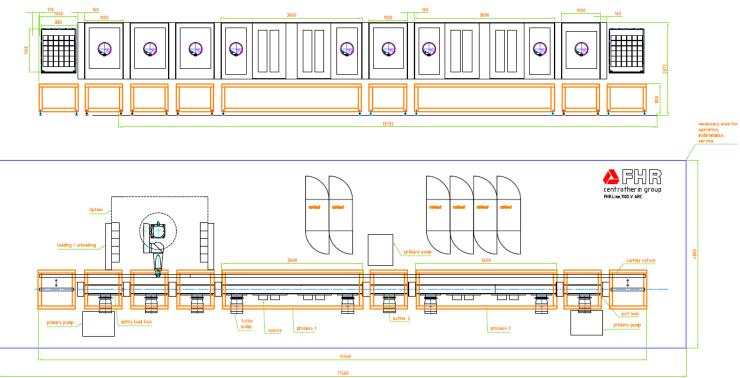
Vacuum

end pressure	\leq 2 x 10 ⁻⁶ mbar after 8 hours (Equipment was already pumped
	before and vented with CDA, opening time <30 min)
end pressure	\leq 1,5 x 10 ⁻⁶ mbar after 12 hours (Equipment was already pumped
	before and vented with CDA, opening time <30min)

Basic equipment configuration

		Transfer table (under athmosphere)		Entry lock Module 2		Buffer 1 Module 3		Buffer 2 Module 4		Pr	ocess	cham	ber 1 Module	5		Buffer 3 Module 6			Process ch	namber	2 Module	7		Exit lock Module 8		Transfer table (under athmosphere)
	1200 mm	Module 1 885 mm		0		0		0		0	Ū	ox	TiOx	ο		o		o	Si		Si	o		ο		Module 9
Coater length	15560	1000	170	1000	170	1000	170	1000	170				500		170	1000	170			3600			170	1000	170	1000
Process section	15560	1000	1/0	1000	1/0	1000	1/0	1000	1/0		1	30	1		1/0	1000	1/0		1	3000	1		1/0	1000	1/0	1000
Pump section	9		-	1		1		1		4				4		1		1	+ i		1	1				-
Acceleration section	4									4				1		1		1		-		4		1		
Heaters	2		-	2														1	+	-	_		-			-
Magnetrons dual	4		-	2								1	1						1	-	1					
AMS-DMS power supply	4		-				-						1		-					_	1		-			-
Turbo pump	9		-	1		1		1		1				1	-	1		1		-		1	-	1		
Polycold	9	-	-	1		1		1		1				1	-	1	-	1		-		1	-	1		-
VAT DN 250	3		-	1											1	1		1					1	1		
MFC	29	1		1		1		1				6	6			1	1		6		6			1		-
Flap valve	8	1	1		1		1		1						1		1						1		1	-
Rotary vane pump 250 m ³ /h	2	1	È	1													1							1	Ē	
Screw pump 300 m ³ /h	1	1																								
Roots pump 1000 m ³ /h	3	1		1	1 1																					
Pro Prove and					1																				-	
Carrier	15			1		1		1				3				1			3					1		4

Rough layout plan



Technical data

- length approx. 18,500 mm (overall length)
- width approx. 4,800 mm (including maintenance area)
- height approx. 2,350 mm

Substrate loading/unloading

loading station before load lock chamber for sequential manual loading/moving of carriers

unloading station after exit lock for sequential manual unloading of carriers

DN 250 ISO-K for turbo molecular pump DN 63 ISO-K fore vacuum pump view port DN 100 service flange in the front additional flanges for heaters, vacuum gauges, rotary feedthroughs, reserve flanges DN 16/25/40, etc.

Chambers

vacuum chamber made of stainless steel. chamber frame made of powder coated mild steel pneumatic gate valves

Modules include:

DN 250 ISO-K for turbo molecular pump view port DN 100 service flange in the front additional flanges for heaters, vacuum gauges, rotary feedthroughs, reserve flanges DN 16/25/40, etc. Flap valves VAT

rotary dry pumps	300 m ³ /h and 250 m ³ /h
roots pumps	1,000 m³/h
turbomolecular pumps approx	1,900 I s ⁻¹ for N ₂ and ca. 1,400 I/s for N ₂

gate valves DN 250

Meissner trap with cryo generator

6 x Pirani gauges fore vacuum sensors 1000mbar – 10⁻³ mbar

8 x Penning high vacuum sensors 10^{-3} mbar – 10^{-8} mbar, to measure the end pressure 13 x Baratrons MKS Typ 627 10^{-1} mbar – 10^{-4} mbar, for measurering the process pressure pressure regulation "upstream" - changing of the gas flow with constant pumping atmospheric preasure sensors

Technology

Rotatable sputtering cathodes

- number of cathodes for TiO_x
 8 (4 dual magnetrons)
- brand SCI MC-End block
- target length 1,100 mm
- backing tube diameter
 133 mm
- target-substrate-distance 100 mm

Gas admission system

MFCs for Ar for each sputtering source

all gas lines specified for 5N purity

Power supplies

• 4 x MF bipolar power supplies (AMS-DMS from AE)*

*With one AMS-DMS combination one cathode can be run in some kHz unipolar mode.

Control and visualization

- PC surface
- software based on Windows 7 Professional
- industrial PLC for general control (SIEMENS S7)
- software: visualisation of the whole equipment function
- parallel processing

Electrical power

- aggregate connection 3/N/PE AC 380V/50Hz
- control voltage 24 V

Cooling water

Power supplies (PSU), cathodes and cathode surrounds are cooled by water loops.

The following materials are used in the cooling circuits: stainless steel, copper, brass, plastics, nickel

Guidelines

Guideline for machines 2006/42/EG

Low voltage guideline 2006/42/EG

Guideline for electromagnetic compatibility 2006/95/EG

The Equipment CE-mark

The main electrical cabinet will be compliant with UL electrical standards. Subsequent electrical cabinets will be in compliance with CE standards

Automatization

The automatization consists of carrier return system with station for carriers to load/unload the carrier into the sputtering Equipment with **2 midsized Kuka robots**